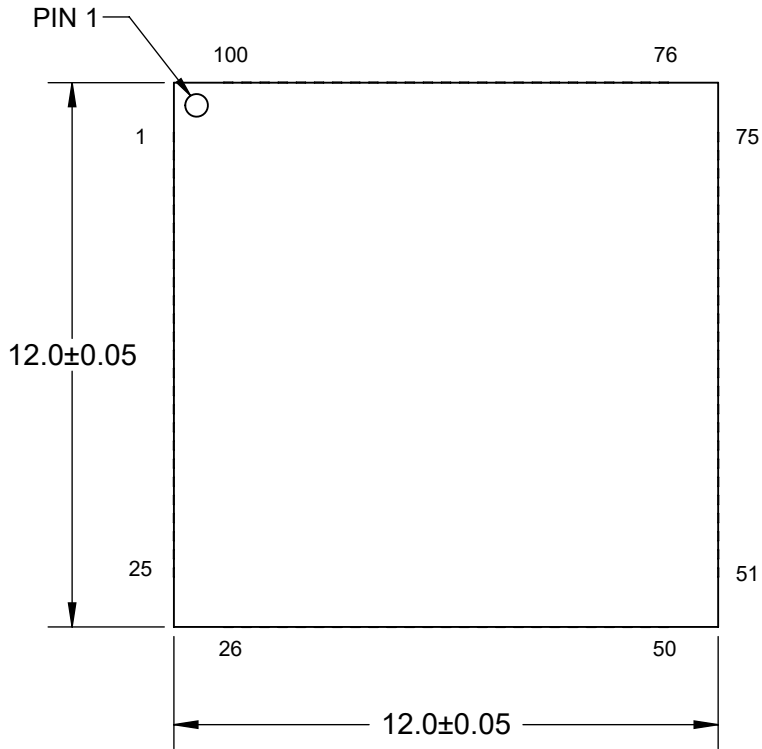
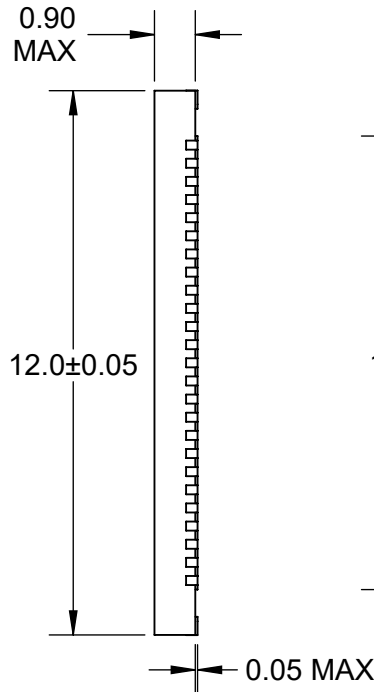


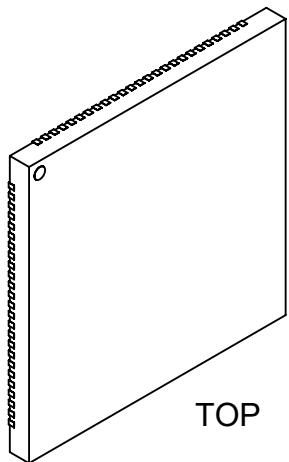
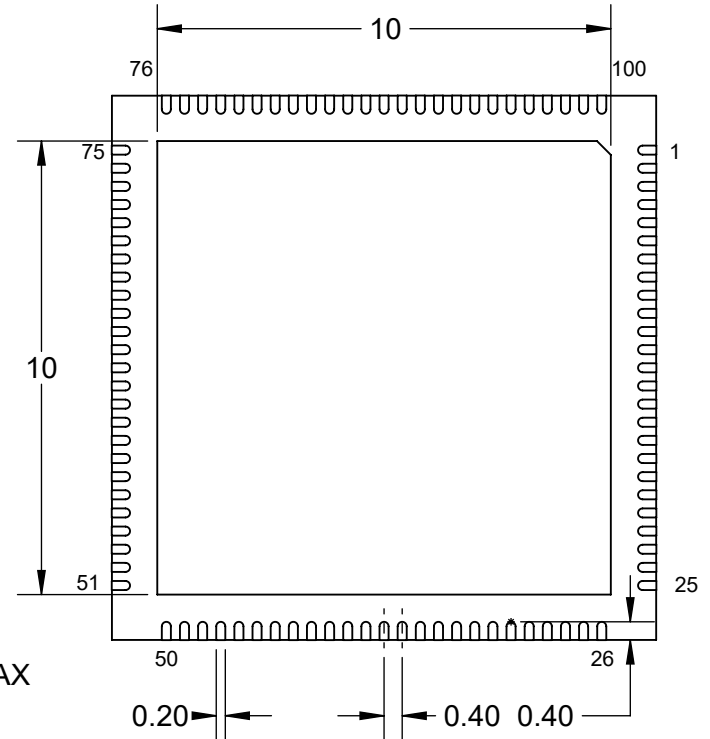
### HCD J9K



### G89 J9K

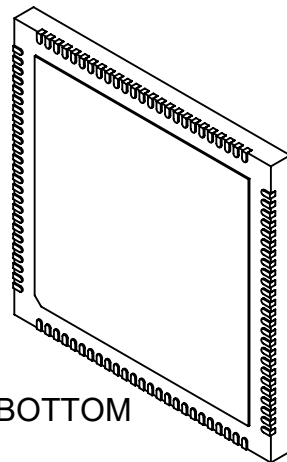


### 6CHCA J9K



TOP

MODEL



BOTTOM

Notes: (Unless Otherwise Specified).

- 1) BODY: PLASTIC, SEMICONDUCTOR GRADE.
- 2) LEAD FRAME: COPPER, C-194 F/H.
- 3) LEAD FRAME PLATING: Ni-Pd-Au.
- 4) FRAME THICKNESS: 0.203mm.
- 5) DIE PAD: 10 x 10mm EXPOSED BOTTOM.
- 6) JEDEC OUTLINE: MO-220.
- 7) DIMENSIONS IN mm.

APPROVALS	DATE	<b>TopLine®</b>			
DRAWN T. Au	5/1/2020				
ENG M. Hart	5/1/2020	TITLE 100-LEAD 12mm P0.4mm QFN DAISY CHAIN			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		6:1	A	449940	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 5
REVISED					

85 GM7 < 5 B D5 HH9 F B

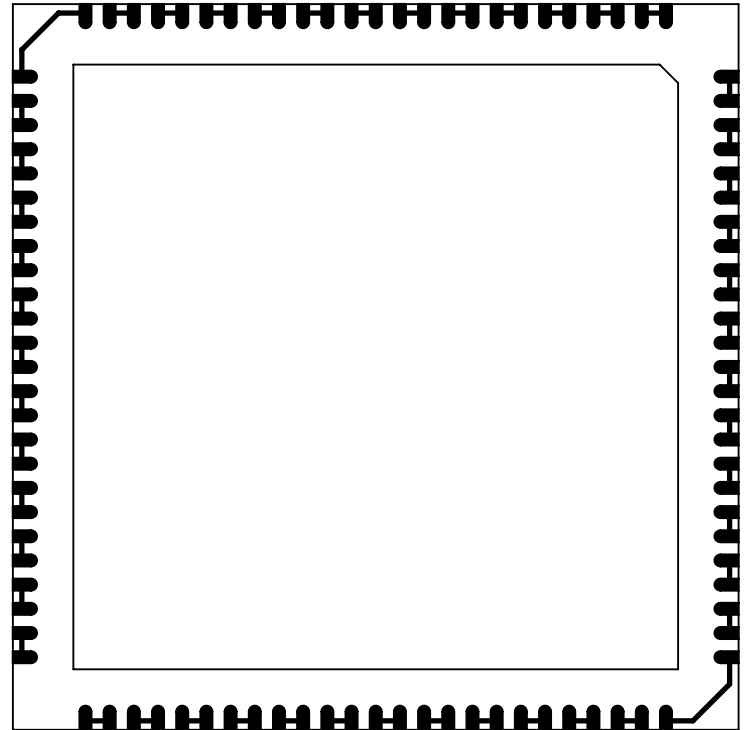
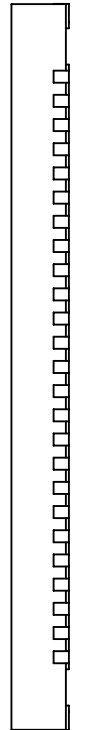
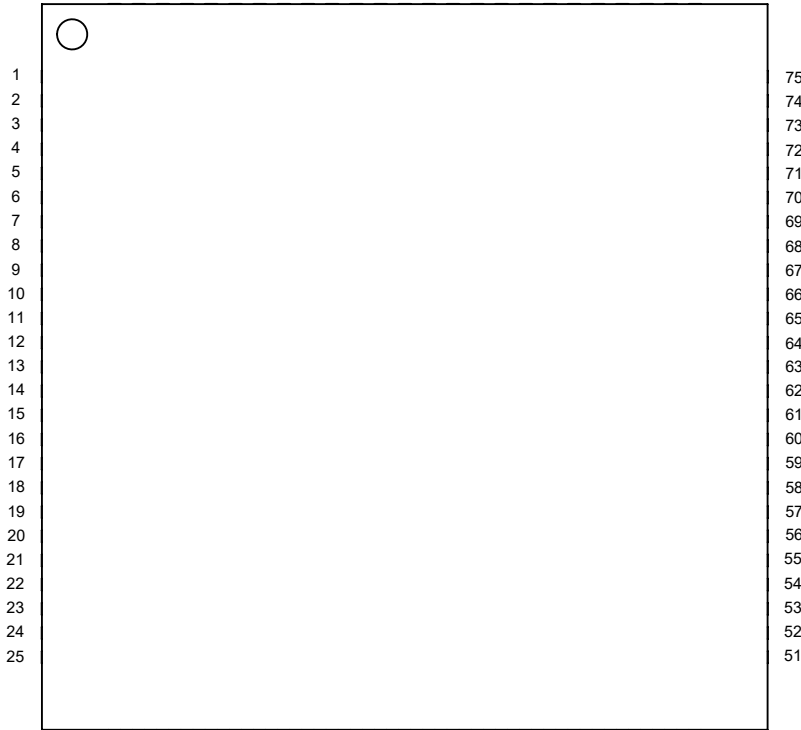
HCD J 9 K

G 8 9 J 9 K

6 CHCA J 9 K

100 99 98 97 96 95 94 93 92 91 90 89 88 87 86 85 84 83 82 81 80 79 78 77 76

76 77 78 79 80 81 82 83 84 85 86 87 88 89 90 91 92 93 94 95 96 97 98 99 100

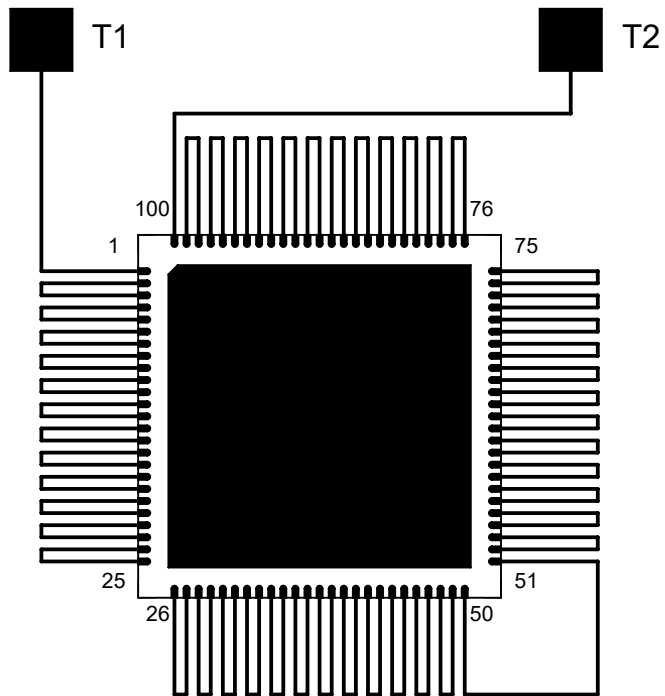


0.9  
MAX

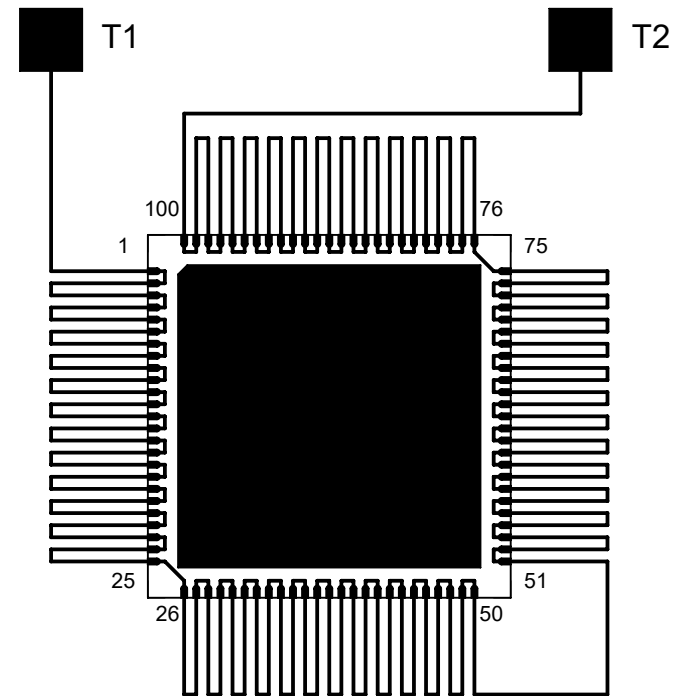
TOP SIDE ENCAPSULATION

NOTE:  
1. PACKAGE DAISY CHAIN BY WIRE BONDING TO INTERNAL BOND PADS.

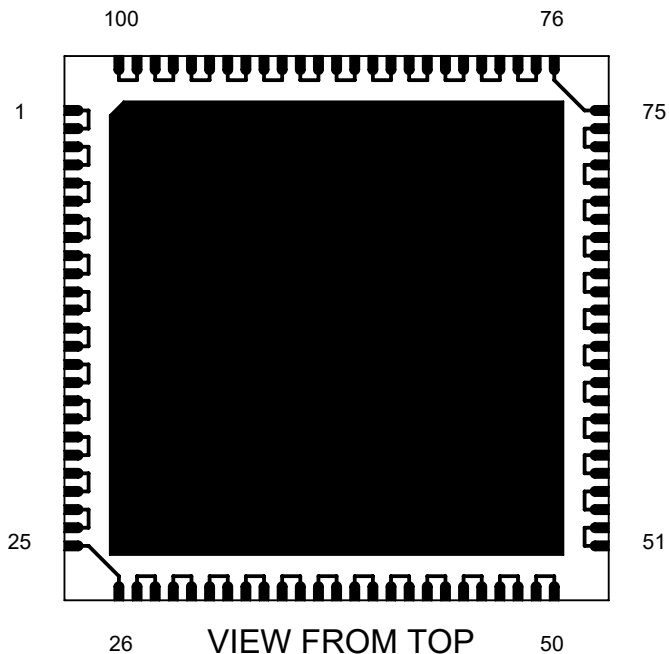
<b>TopLine®</b>			
TITLE 100-LEAD 12mm P0.4mm QFN DAISY CHAIN			
SCALE 8:1	SIZE A	DRAWING NO. 449940	REV A
DO NOT SCALE DRAWING			SHEET 2 OF 5



RECOMMENDED  
PCB PADS




AFTER MOUNTING  
ON PCB

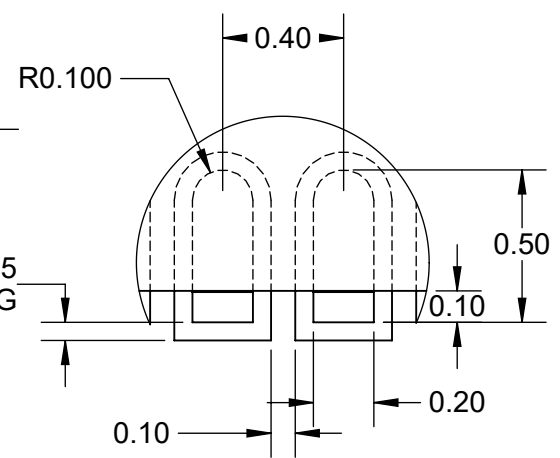
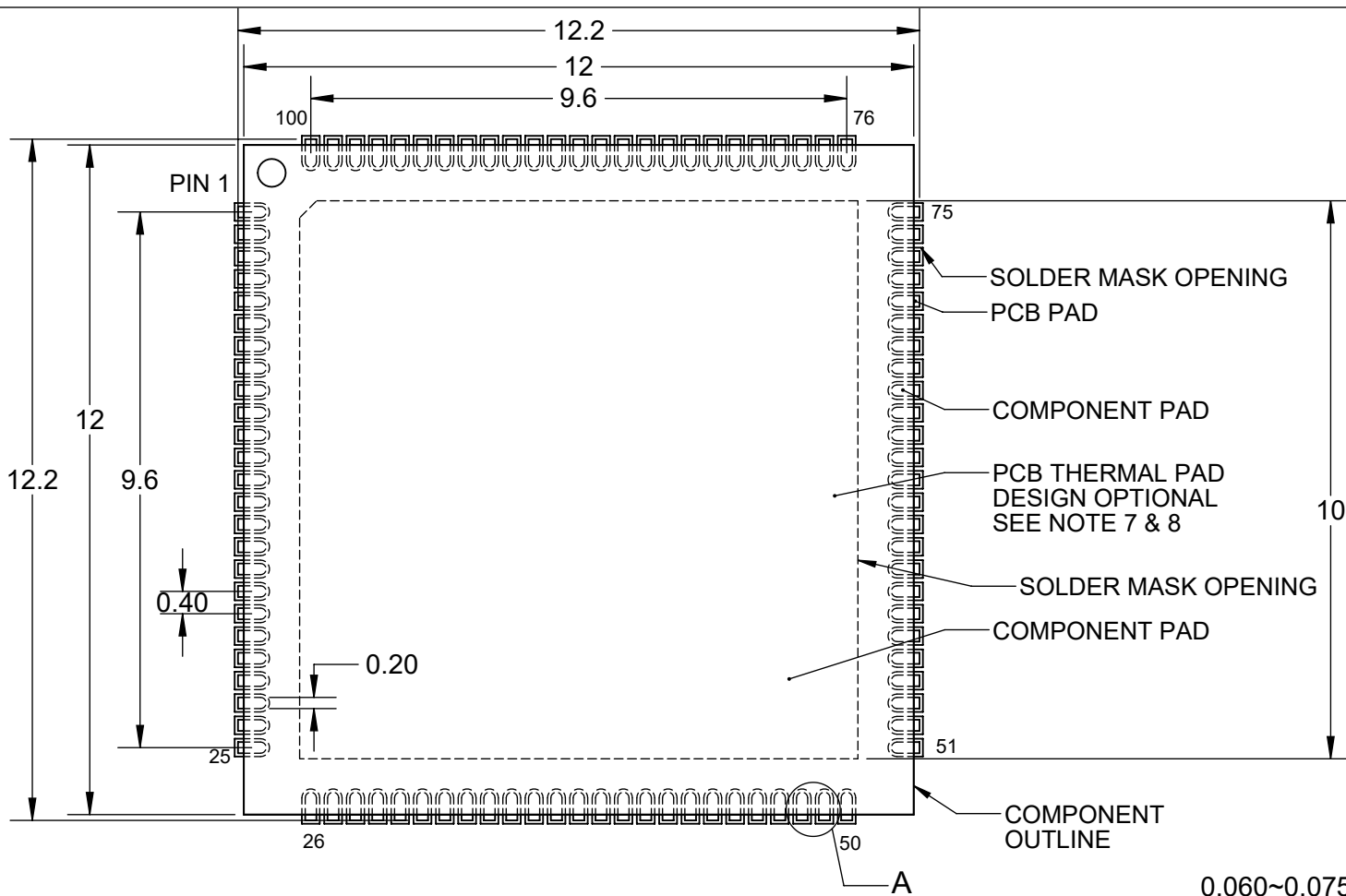


VIEW FROM TOP

85-GM7<5-B B9H'@GH		
PINS	PINS	PINS
1 ~ 2	3 ~ 4	5 ~ 6
7 ~ 8	9 ~ 10	11 ~ 12
13 ~ 14	15 ~ 16	17 ~ 18
19 ~ 20	21 ~ 22	23 ~ 24
25 ~ 26	27 ~ 28	29 ~ 30
31 ~ 32	33 ~ 34	35 ~ 36
37 ~ 38	39 ~ 40	41 ~ 42
43 ~ 44	45 ~ 46	47 ~ 48
49 ~ 50	51 ~ 52	53 ~ 54
55 ~ 56	57 ~ 58	59 ~ 60
61 ~ 62	63 ~ 64	65 ~ 66
67 ~ 68	69 ~ 70	71 ~ 72
73 ~ 74	75 ~ 76	77 ~ 78
79 ~ 80	81 ~ 82	83 ~ 84
85 ~ 86	87 ~ 88	89 ~ 90
91 ~ 92	93 ~ 94	95 ~ 96
97 ~ 98	99 ~ 100	

			
TITLE		100-LEAD 12mm P0.4mm QFN DAISY CHAIN	
SCALE	SIZE	DRAWING NO.	REV
4:1	A	449940	A
DO NOT SCALE DRAWING			SHEET 3 OF 5

D7 6 C5 F8 @ MCI H  
 8 A9 BG CBG B AA  
 J 9 K : FCA HCD

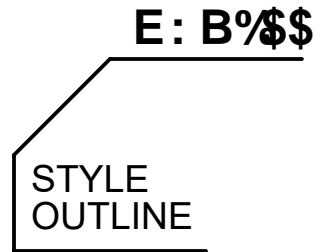


Notes: (Unless Otherwise Specified).

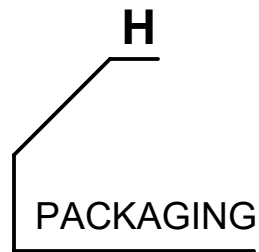
- 1) DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.  
 DESIGNERS SHOULD USE THEIR OWN KNOWLEDGE BASE WHEN DESIGNING THE PCB.
- 2) SURROUND EACH SIDE OF I/O PERIMETER PADS WITH 0.060~0.075 mm (NSMD) SOLDER MASK OPENING (2.4~3.0mils) OPTIONALLY OK TO USE RECTANGLE (NSMD) MASK OPENING AROUND I/O PADS.
- 3) ROUNDED PCB LAND PADS REDUCE SOLDER BRIDGING. PAD CHAMFER ANGLE MAY VARY.
- 4) PCB LANDS SHOULD BE 0.2mm LONGER THAN THE PACKAGE I/O PADS.
- 5) THE WIDTH OF PERIMETER PCB PADS SHOULD MATCH (1:1) THE WIDTH OF THE PACKAGE PADS.
- 6) REFER TO INDUSTRY REFERENCES SUCH AS IPC-SM-782 FOR PCB LAND PATTERN DESIGN.
- 7) THERMAL GROUND PADS MAY BE CHANGED TO SUITE REQUIREMENTS OF THE DESIGNER.
  - A) MAKE COPPER THERMAL PAD AS LARGE AS POSSIBLE.
  - B) DRILL MULTIPLE THERMAL VIAS 0.25~0.33mm DIAMETER USING 0.8~1.2mm PITCH GRID.
  - C) PLATE THERMAL VIA BARRELS WITH 1-OUNCE COPPER (18µm).
  - D) TENT (COVER) THERMAL VIAS WITH SOLDER MASK 0.1mm LARGER THAN THE VIA DIAMETER.
- 8) STENCIL DESIGN MAY BE CHANGED TO SUIT REQUIREMENTS OF THE DESIGNER.
  - A) LASER CUT STENCIL 0.125mm (5mil) THICK. APERTURE SIZE-TO-LAND RATIO OF 1:1.
  - B) THE SOLDER PASTE OPENING IN THE THERMAL PAD AREA SHOULD BE A MATRIX ARRAY OF SMALLER APERTURES INSTEAD OF ONE LARGE APERTURE TO CONTROL PASTE AMOUNTS.
  - C) APPLY 50% TO 80% SOLDER PASTE COVERAGE IN THE PAD AREA.

<b>TopLine®</b>			
TITLE 100-LEAD 12mm P0.4mm QFN DAISY CHAIN			
SCALE 8:1	SIZE A	DRAWING NO. 449940	REV A
DO NOT SCALE DRAWING			SHEET 4 OF 5

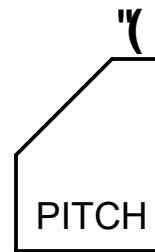
# D5FH'BI A69F-B; 'GMGH9A



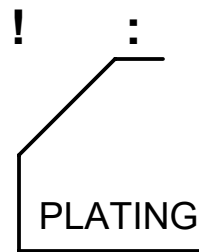
QUAD FLAT  
NO LEAD  
100 LEADS



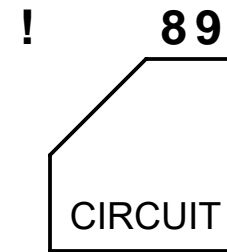
M = TUBE  
T = TRAY  
E = CUT TAPE  
E7A = 7" REEL



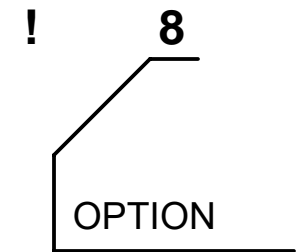
.4 = 0.4MM



F = Ni Pd Au  
T = MATTE TIN  
Sn100



DE = DAISY CHAIN  
ISO = ISOLATED  
BLANK = DUMMY



BLANK = DUMMY  
D = DUMMY DIE

D5FH'BI A69F	<del>85-GM</del> 7<5-B	D57?5; -B;	Fc<G DVI: F99	D@HB;	<del>8I AAM</del> 8-9
QFN100T.4-F-DE-D	YES	JEDEC TRAY	YES	NiPdAu	YES
QFN100M.4-F-DE-D	YES	TUBE	YES	NiPdAu	YES
QFN100E.4-F-DE-D	YES	TAPE	YES	NiPdAu	YES
QFN100T.4-F-ISO	ISOLATED	JEDEC TRAY	YES	NiPdAu	NO
QFN100E.4-F-ISO	ISOLATED	TAPE	YES	NiPdAu	NO

OTHER PART NUMBER COMBINATIONS AVAILABLE. CONTACT TOPLINE.

<b>TopLine®</b>			
TITLE 100-LEAD 12mm P0.4mm QFN DAISY CHAIN			
SCALE NONE	SIZE A	DRAWING NO. 449940	REV A
DO NOT SCALE DRAWING			SHEET 5 OF 5